

Docket No.: 56937-071



PATENT

SPW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 20277
Hiroaki TAKEZAWA, et al. : Confirmation Number: 4692
Application No.: 10/613,042 : Group Art Unit: 1751
Filed: July 07, 2003 : Examiner: Mark T. Kopek
For: CONDUCTIVE ADHESIVE AGENT, PACKAGING STRUCTURE, AND METHOD FOR
MANUFACTURING THE SAME STRUCTURE :

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Supplemental Information Disclosure Statement is being filed submitting the references cited in European Search Report filed October 19, 2004, under Rule 37 CFR 1.97(i), wherein applicants are submitting references before the grant of a patent to be placed in the file.

Accordingly, copies of the references as listed on the attached Form PTO-1449 are submitted herewith for placement in the file. No certification or fees are deemed necessary.

Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

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Date: October 22, 2004



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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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